

#### **40V NPN SMALL SIGNAL TRANSISTOR IN SOT523**

#### **Features**

- BV<sub>CEO</sub> > 40V
- I<sub>C</sub> = 600mA Collector Current
- Epitaxial Planar Die Construction
- Ultra-Small Surface Mount Package
- Complementary PNP Type: MMBT2907AT
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

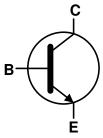
#### **Mechanical Data**

- Case: SOT523
- Case Material: Molded Plastic. "Green" Molding Compound.
   UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.002 grams (Approximate)

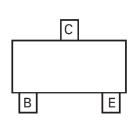








Device Symbol



Pin-out Top View

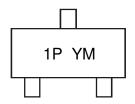
#### **Ordering Information** (Note 4)

Product	Status	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMBT2222AT-7-F	Active	AEC-Q101	1P	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

#### **Marking Information**



1P = Product Type Marking Code YM = Date Code Marking Y = Year (ex: D = 2016)

M = Month (ex: 9 = September)

Date Code Key

Year	2016	2	2017	2018	2019	2020	2021	202	2 20	23	2024	2025	2026
Code	D		E	F	G	Н		J	ŀ	<	L	М	N
Mont	h	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	)	1	2	3	4	5	6	7	8	9	0	N	D



# Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	75	V
Collector-Emitter Voltage	$V_{\sf CEO}$	40	V
Emitter-Base Voltage	$V_{EBO}$	6	V
Collector Current	lc	600	mA

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	Pd	150	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	833	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## ESD Ratings (Note 6)

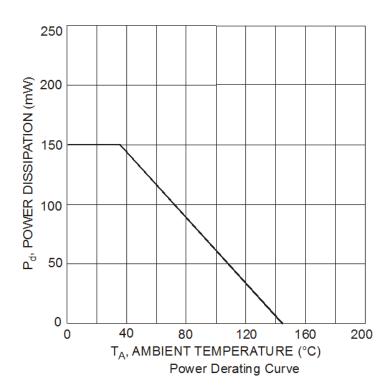
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

- 5. For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

  6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

## **Thermal Characteristics and Derating Information**





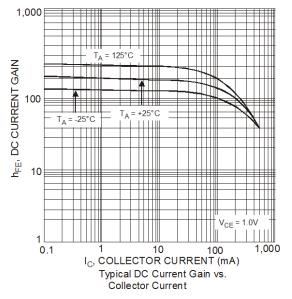
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

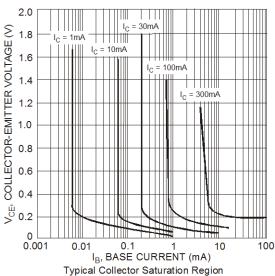
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)	-		•		
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	75	_	V	$I_C = 10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	40	_	V	$I_C = 1 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6	_	V	$I_E = 10\mu A, I_C = 0$
Collector Cutoff Current	I <sub>CEX</sub>	_	10	nA	$V_{CE} = 60V$ , $V_{EB(OFF)} = 3V$
Base Cutoff Current	I <sub>BL</sub>	_	20	nA	$V_{CE} = 60V, V_{EB(OFF)} = 3V$
ON CHARACTERISTICS (Note 7)			1		
DC Current Gain	h <sub>FE</sub>	35 50 75 100 40	  300 	_	$I_{C} = 100\mu A, V_{CE} = 10V$ $I_{C} = 1.0mA, V_{CE} = 10V$ $I_{C} = 10mA, V_{CE} = 10V$ $I_{C} = 150mA, V_{CE} = 10V$ $I_{C} = 500mA, V_{CE} = 10V$
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	0.3 1.0	٧	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$ $I_C = 500 \text{mA}, I_B = 50 \text{mA}$
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.6	1.2 2.0	V	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$ $I_C = 500 \text{mA}, I_B = 50 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	$C_{obo}$	_	8	pF	$V_{CB} = 10V$ , $f = 1.0MHz$ , $I_E = 0$
Input Capacitance	Cibo	_	30	pF	$V_{EB} = 0.5V$ , $f = 1.0MHz$ , $I_{C} = 0$
Input Impedance	h <sub>ie</sub>	0.25	1.25	kΩ	
Voltage Feedback Ratio	h <sub>re</sub>	_	4.0	x 10 <sup>-4</sup>	$V_{CE} = 10V, I_{C} = 10mA,$
Small Signal Current Gain	h <sub>fe</sub>	75	375	_	f = 1.0MHz
Output Admittance	h <sub>oe</sub>	25	200	μS	
Current Gain-Bandwidth Product	f <sub>T</sub>	300	_	MHz	$V_{CE} = 20V, I_{C} = 20mA,$ f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	$t_D$	_	10	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA,
Rise Time	t <sub>R</sub>	_	25	ns	$V_{BE(OFF)} = -0.5V, I_{B1} = 15mA$
Storage Time	ts	_	225	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA
Fall Time	t <sub>F</sub>	_	60	ns	$I_{B1} = -I_{B2} = 15mA$

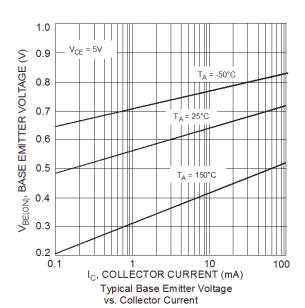
Notes: 7. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.

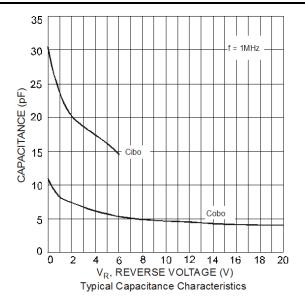


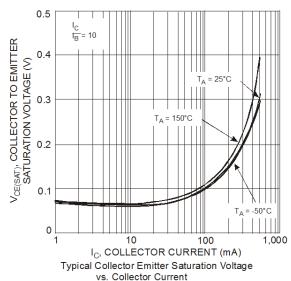
## Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)











1,000

V<sub>CE</sub> = 5V

NHW

LONGON

100

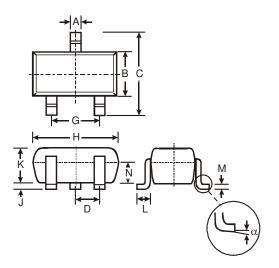
I<sub>C</sub>, COLLECTOR CURRENT (mA)

Typical Gain Bandwidth Product vs. Collector Current



## **Package Outline Dimensions**

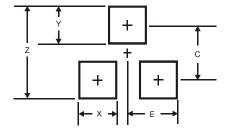
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT523							
Dim	Min	Max	Тур					
Α	0.15	0.30	0.22					
В	0.75	0.85	0.80					
С	1.45	1.75	1.60					
D	_	_	0.50					
G	0.90	1.10	1.00					
Н	1.50	1.70	1.60					
J	0.00	0.10	0.05					
K	0.60	0.80	0.75					
L	0.10	0.30	0.22					
M	0.10	0.20	0.12					
N	0.45	0.65	0.50					
α	0°	8°						
All	All Dimensions in mm							

# Suggested Pad Layout

 $Please\ see\ http://www.diodes.com/package-outlines.html\ for\ the\ latest\ version.$ 



Dimensions	Value (in mm)
Z	1.8
Х	0.4
Υ	0.51
С	1.3
E	0.7



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